

LNA4401L

GaAlAs Infrared Light Emitting Diode

For optical control systems

■ Features

- High-power output, high-efficiency: $P_O = 10$ mW (typ.)
- Fast response and high-speed modulation capability: $f_C = 20$ MHz (typ.)
- TO-18 standard type package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	190	mW
Forward current	I_F	100	mA
Pulse forward current *	I_{FP}	1	A
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +100	$^\circ\text{C}$

Note) *: $f = 100$ Hz, Duty cycle = 0.1%

■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

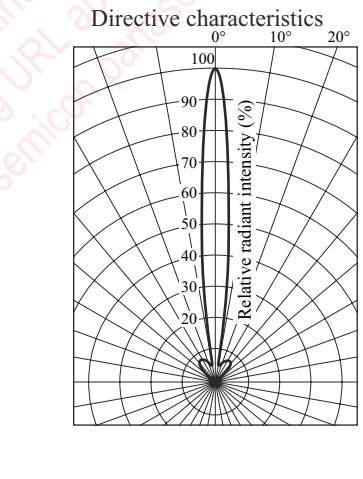
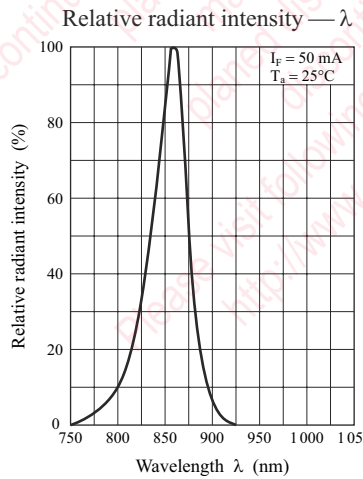
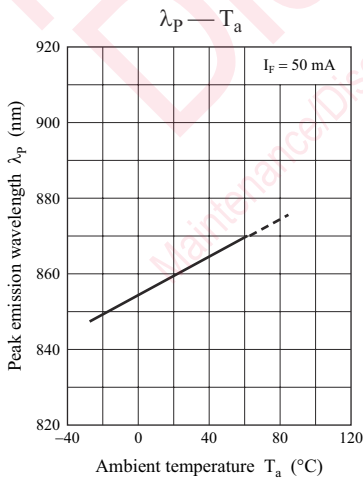
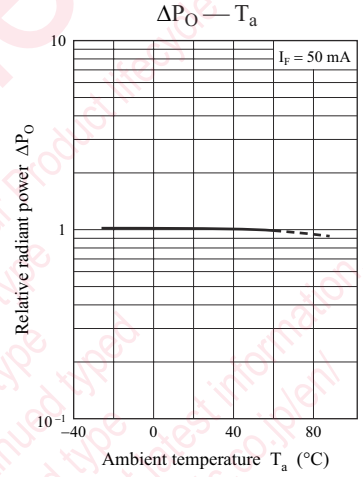
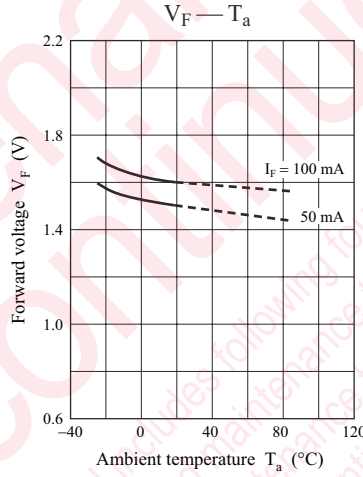
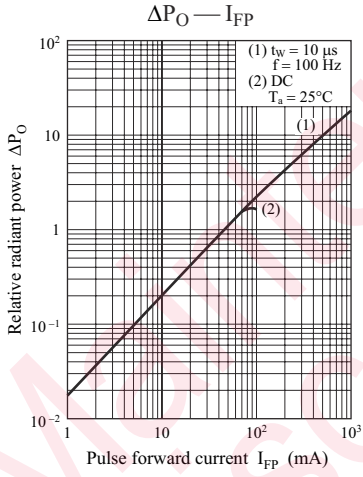
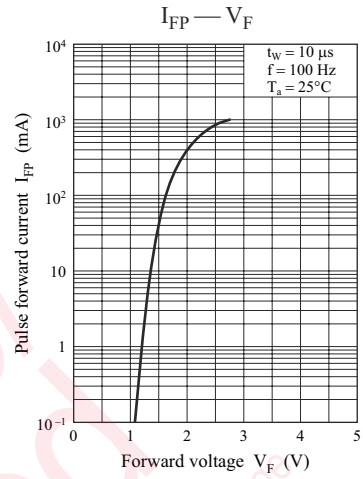
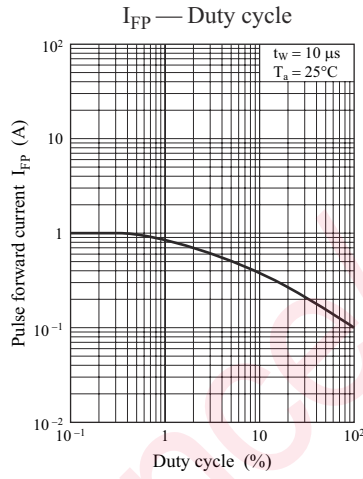
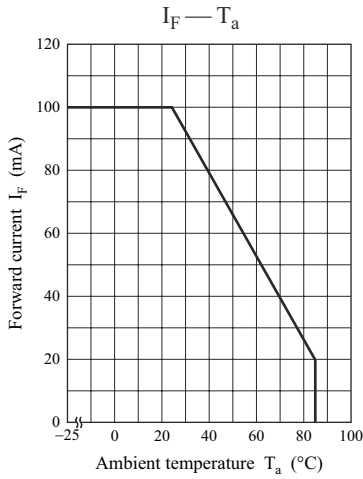
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Radiant power	P_O	$I_F = 50$ mA	6	10		mW
Reverse current	I_R	$V_R = 3$ V			10	μA
Forward voltage	V_F	$I_F = 100$ mA		1.6	1.9	V
Peak emission wavelength	λ_p	$I_F = 50$ mA		860		nm
Spectral half band width	$\Delta\lambda$	$I_F = 50$ mA		40		nm
Half-power angle	θ	The angle when the radiant power is halved.		6		$^\circ$
Cutoff frequency *	f_C	$I_{FP} = 50$ mA + 10 mA[p-p]		20		MHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *: Modulation total power output 3 dB frequency to fall from 1 MHz.

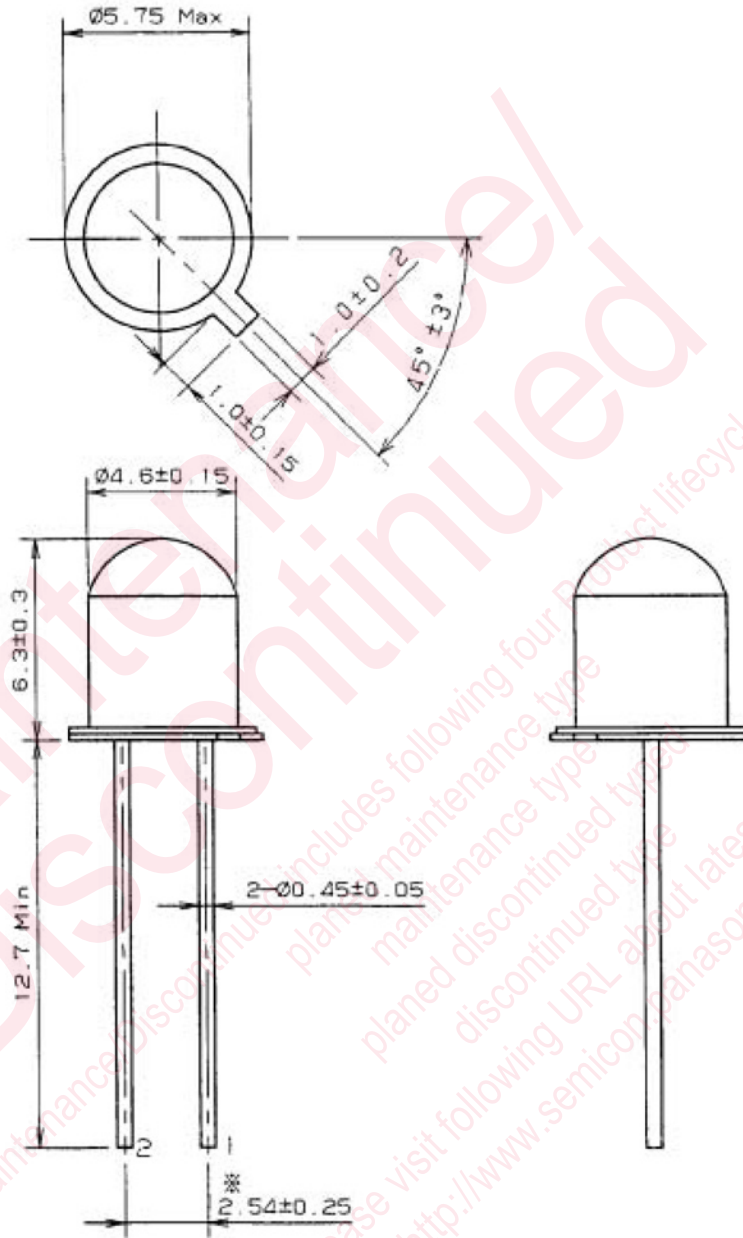
Cutoff frequency:

$$f_C : 10 \times \log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 1 \text{ MHz}} = -3$$



■ Package (Unit: mm)

MECLTN2S0001



- Pin name
 - 1: Cathode
 - 2: Anode

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